

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	73	205/147.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 08:57
L2	209	jet adj plating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 09:03
L3	84	jet adj plating and (wafer semiconductor microelectronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/08 09:03